



—Workable by quick-press—
Bonding sheet **“AE91”**

Example of use

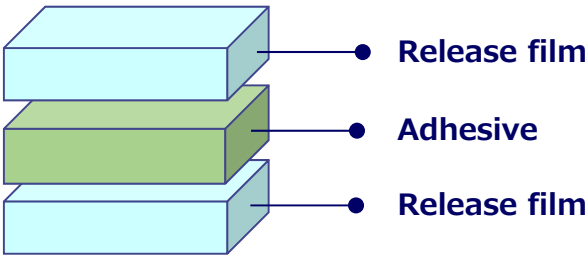
- Smartphone
- Tablet PC
- Laptop computer



Characteristics

- Good circuit-filling by quick-press.
- High performance in ion migration resistance with frame retardancy equivalent to V-0 (UL94).

Product structure



Appearance

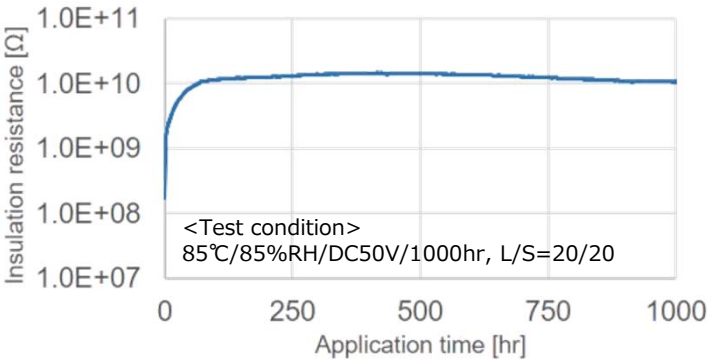


Product Properties

Item	Unit	AE91
90° Peel strength (Peeling 1mil/1oz FCCL)	N/cm	21
Solder heat resistance	℃	288
Flammability	—	V-0
Circuit filling by quick-press (185℃)	-	60 sec.
HHBT	—	> 1000hr
Tg	℃	74
Elastic modulus	GPa	1.1

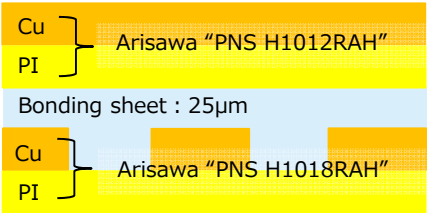
Sample making condition (pressing) : 160℃×3MPa×60min

<Ion migration resistance>



<Test sample structure>

for Circuit filling test by quick-press



【Circuit filling test pattern】
L/S=50/50 to 100/100



Sales & Marketing Department
Tokyo Head Office: Yanagibashi 2-12-5, Taito-ku, Tokyo 111-0052, Japan Tel : +81-3-3861-1110
Kansai: Tsumori 3-7-27, Nishinari-ku, Osaka 557-0062, Japan Tel : +81-6-4703-3168

The data in this document are measured values, not for guaranteed.